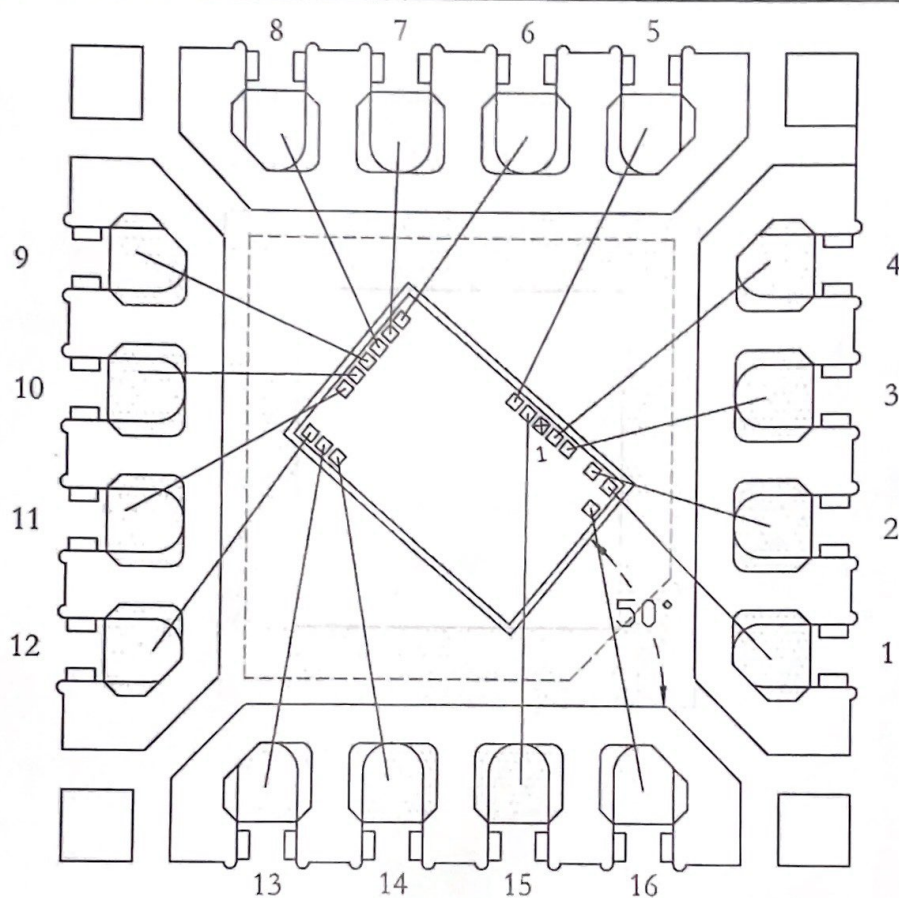
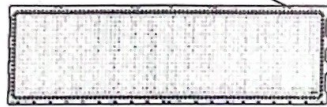
 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO., LTD.				客户代码 Customer No.	008	线号 Drawing No.	HY-PX-008-755 A	
焊线图纸 Bonding Diagram				产品名称 Product Type	HS16F2612		封装类型 PKG Type	QFN16L(3X3X0.75-P0.5)
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线股数 NO. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	焊线材料型号(绿色环保) Compound Type (Green)	LF 载体尺寸 LF Pad Size	
合金 Alloy	20	18	19897	1344	761	首选(Preferred): CEL-92201JF 备选(Optional): EME-G77014M	QFN16L(3X3X0.75-P0.5)(75X75)(1black) (1000X1900μm ²)	
客户图号 Customer drawing NO.								



封装特选方向 (载片): L/F Direction (D/A):	椭圆孔 	补图: Chip photo:	特殊说明 Special Instructions: DB注意: 1. 芯片居中放置并逆时针旋转50°; WB注意: 1. 数字为不打线pad个数;
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说明 Introduction	贴片胶类型 epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPP(μm)	最小焊盘间距 Min BPP(μm)	焊盘厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	贴片通宽度 Sheet line (μm)	晶圆尺寸 Wafer Size	是否导电 Low-RK (Flammable)	晶圆厚度 Wafer Thickness
A芯: DIE A	导电胶 (conductivity) S220	HS5159	1135*709(μm) 44.69*27.91(mil)	50*50	70	0.8	是/Yes	60	8	否/NO	200
B芯: DIE B											
C芯: DIE C											
编制 Prepared by	陈林. 2024.4.29		制图日期 Create Date	2024/4/27		生效日期 Effective Date	客户确认签字/盖章: Customer Signature				
研发审核 R&D Check	陈林. 2024.4.29		产品工程审核 PE Check			批准 Approved by	 2024.4.29				

温馨提示: 图纸为生产下线的唯一依据, 请认真确认, 我可依图生产, 如出低错, 后果严重不可估量, 谢谢!
 Warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you.